M-QFN PACKAGE

M-QFN AS SHIELDED COVER

LEAD FRAME: Cu (C-194F/H)
WALLS: SEMICONDUCTOR GRADE MOLD COMPOUND

APPLICATION NOTES
USING M-QFN AS SHIELDED DOME LID ASSEMBLY

COMBINED PACKAGE DIMENSIONS

<table>
<thead>
<tr>
<th>REF</th>
<th>DES</th>
<th>mm</th>
<th>MILS</th>
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<tbody>
<tr>
<td>Z</td>
<td>CAVITY</td>
<td>1.27</td>
<td>50</td>
</tr>
<tr>
<td>C1</td>
<td>LID</td>
<td>0.635</td>
<td>25</td>
</tr>
<tr>
<td>C2</td>
<td>QFN</td>
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<tr>
<td>A1</td>
<td>LID</td>
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<td>32</td>
</tr>
<tr>
<td>A</td>
<td>QFN</td>
<td>0.81</td>
<td>32</td>
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<tr>
<td>H</td>
<td>TOTAL HEIGHT</td>
<td>1.62</td>
<td>64</td>
</tr>
</tbody>
</table>

TOLERANCE UNLESS NOTED

X X X  ± 0.3
X X X  ± 0.03
X X X X  ± 0.003

ANGLES: 90°

ALL DIMENSIONS IN MILLIMETERS

M-QFN ASSEMBLY

M-QFN DOME COVER

CAVITY FLOOR

SECTION A-A

M-QFN DOME PACKAGE

M-QFN CAVITY PACKAGE

M-QFN AS SHIELDED DOME LID